

EXTREME PERFORMANCE HIGH-DENSITY ARRAYS

(0.80 mm) .0315" x (1.80 mm) .071" PITCH





High-speed mezzanine connector and cable in one product family



BGA attach to board for greater density and optimized trace breakout region



Two reliable points of contact with a 1.14 mm wipe

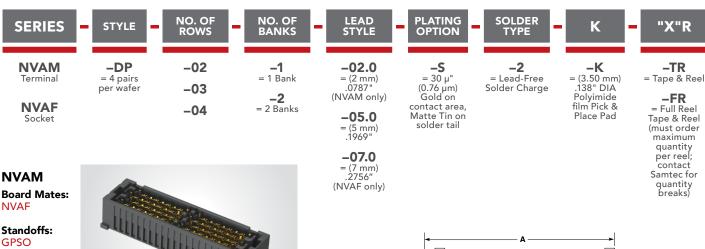
KEY SPECIFICATIONS (NVAM/NVAF)

TOTAL PAIRS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLT- AGE	LEAD-FREE SOLDERABLE
Up to 32 pairs	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.1 A per pin (signal) 9.6 A per pin (ground)	200 VAC/283 VDC	Yes

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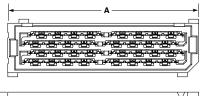
0.80 mm x 1.80 mm PITCH • EXTREME PERFORMANCE ARRAYS

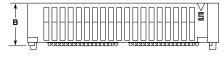


NO. OF BANKS	A
-1	(21.75) .856
-2	(37.75) 1.486

LEAD STYLE	В
-02.0	(5.46) .215
-05.0	(8.46) .333

NO. OF ROWS	с
-02	(7.80) .307
-03	(9.60) .378
-04	(11.40) .449





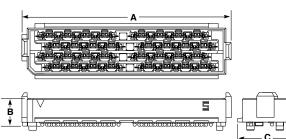


View complete specifications at: samtec.com?NVAM

NVAF Board Mates: NVAM

Standoffs: GPSO





NO. OF BANKS	A
-1	(20.25) .797
-2	(36.25) 1.427

(4.80)

.189

.268

LEAD STYLE

-05.0

-07.0

MATED HEIGHTS*				
	NVAM LEAD STYLE			
NVAF LEAD STYLE	-02.0	-05.0		
-05.0	(7.00) .276	(10.00) .394		
-07.0	(9.00) .354	(12.00) .472		

AGGREGATE DATA RATE (NRZ)					
1024 1536 Gbps Gbps		2048 Gbps	3072 Gbps	4096 Gbps	
1 B	ank	2 Bank			
2 Row	3 Row	4 Row 2 Row	3 Row	4 Row	
8 Pairs	12 Pairs	16 Pairs	24 Pairs	32 Pairs	

NO. OF ROWS	с
-02	(6.00) .236
-03	(7.80) .307
-04	(9.60) .378

Notes:

Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?NVAF

^{*}Processing conditions will affect mated height.

Mouser Electronics

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Samtec:

NVAM-DP-02-2-02.0-S-2-C-TR